

FIG.3

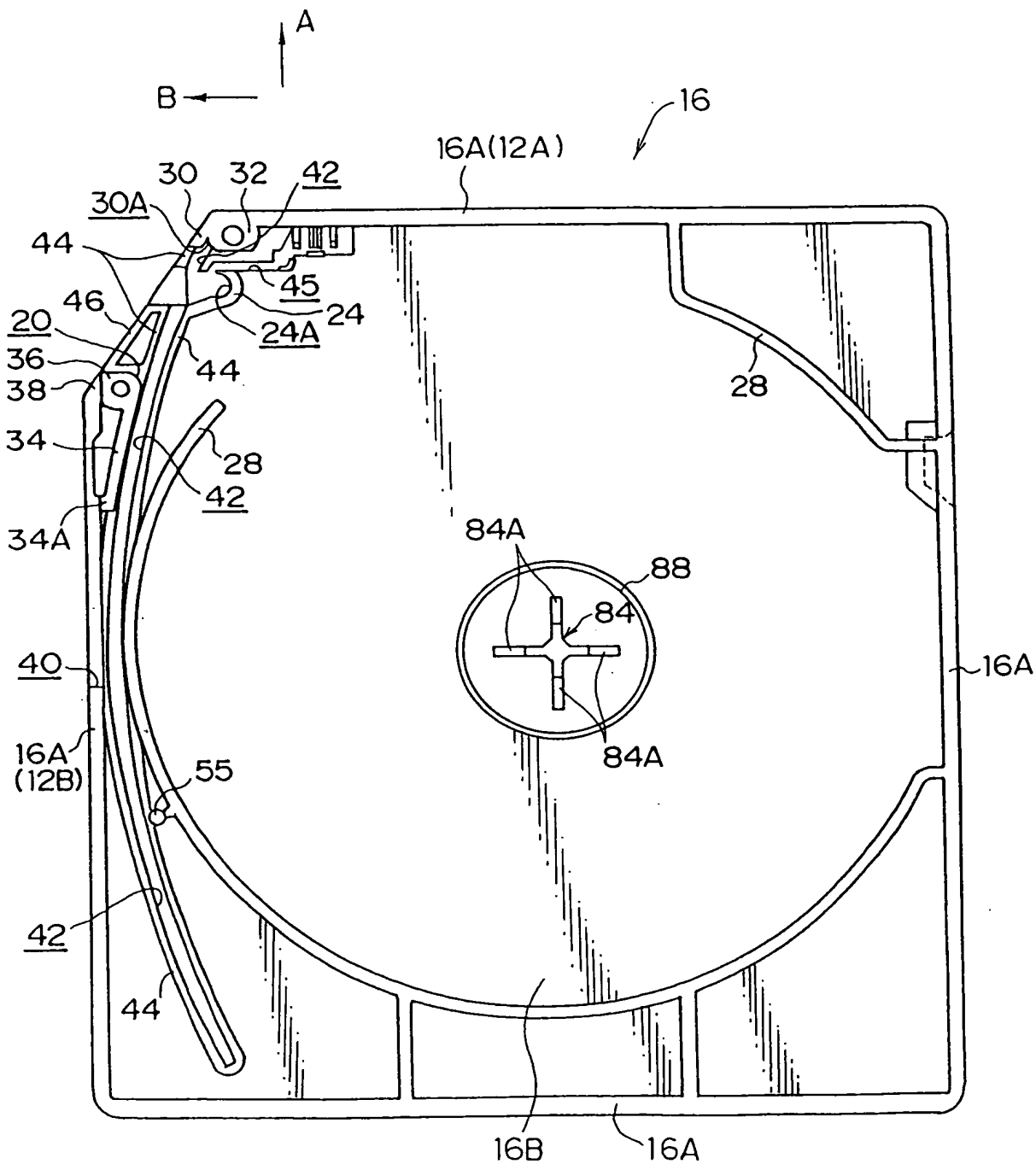
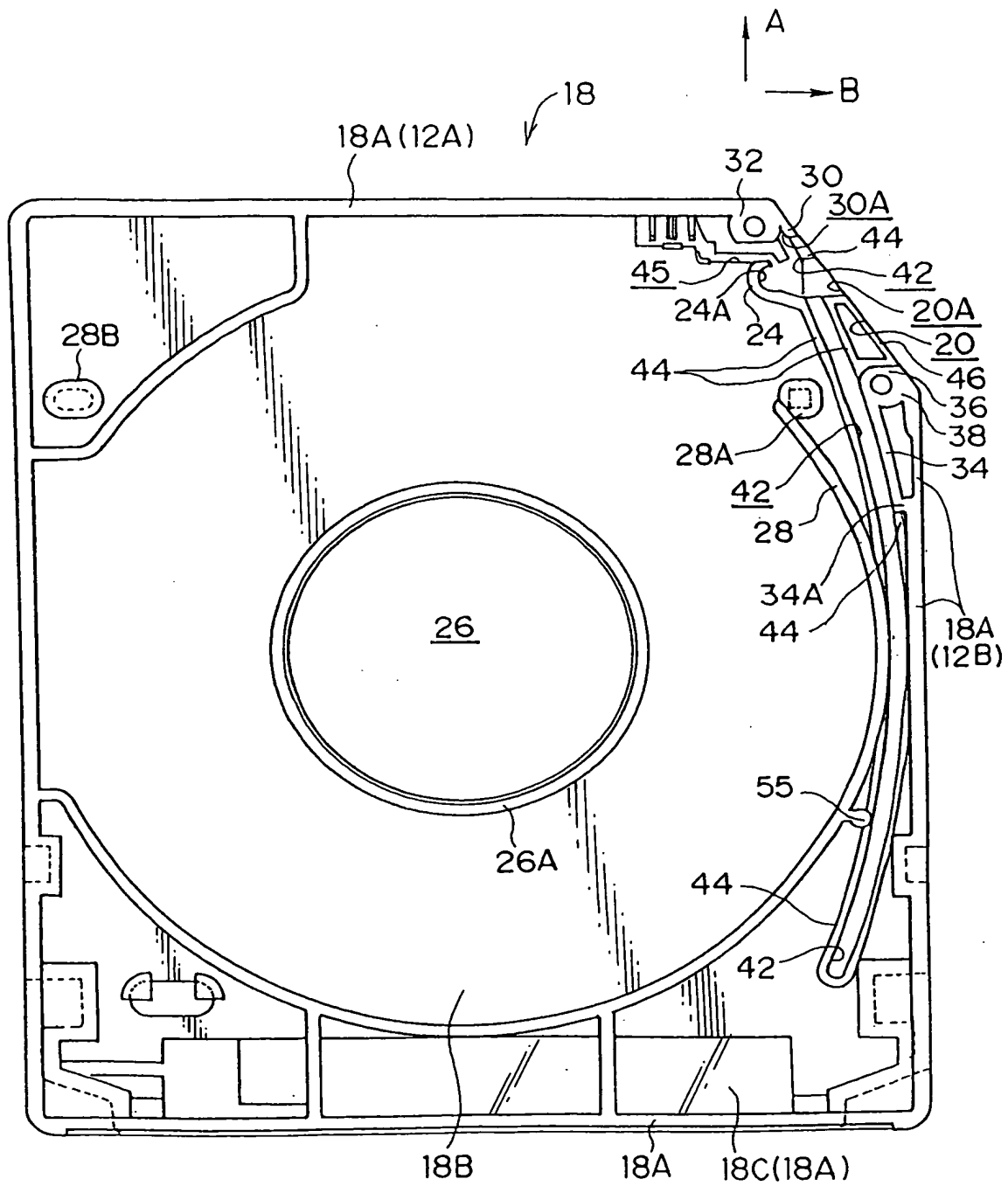


FIG.4



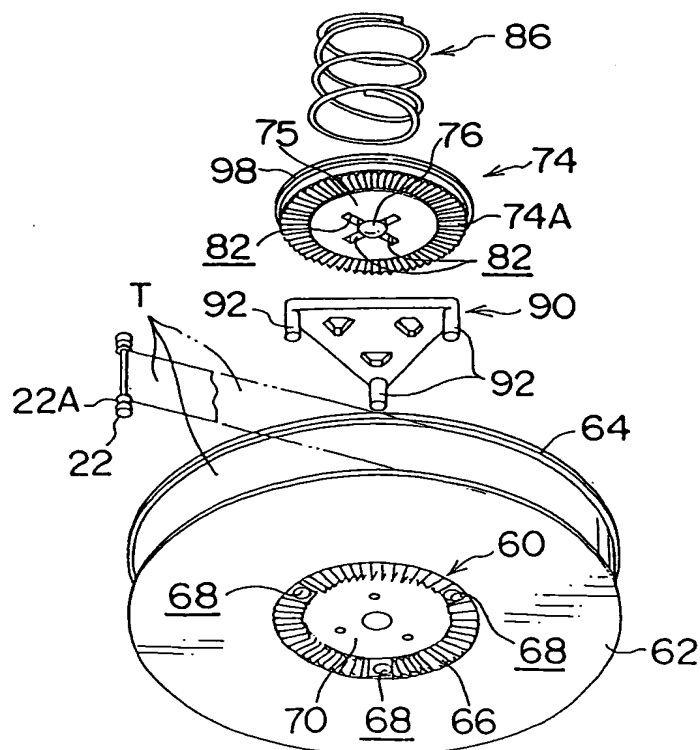
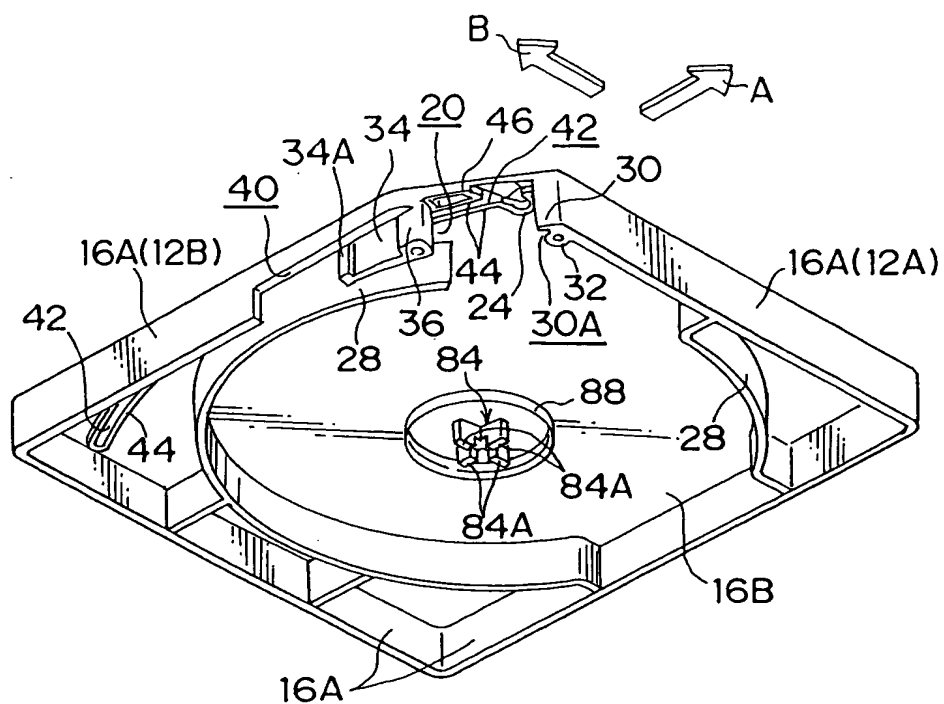


Figure 10 is a detailed cross-sectional view of a multi-layered electronic device assembly. The assembly includes a substrate 10 with multiple layers labeled 12, 16, 18, and 18A. A central component 60 is shown with internal structures 60A and 60B. Other components include 72A, 74A, 78A, 82, 84, 86, 88, 92, 94, 96, and 98. A side view shows a component 100 with a wavy surface 102.

FIG. 8

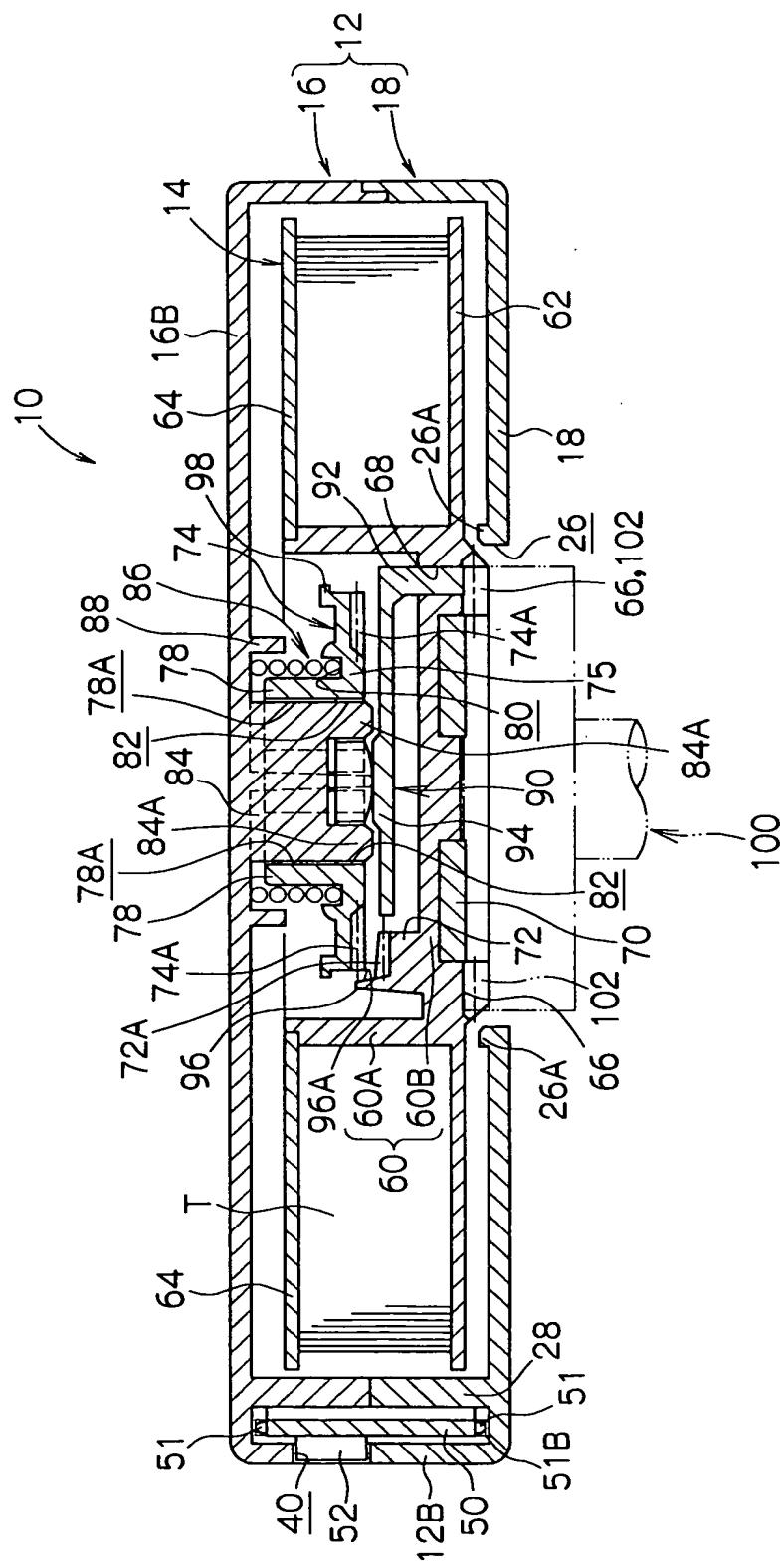


FIG.9

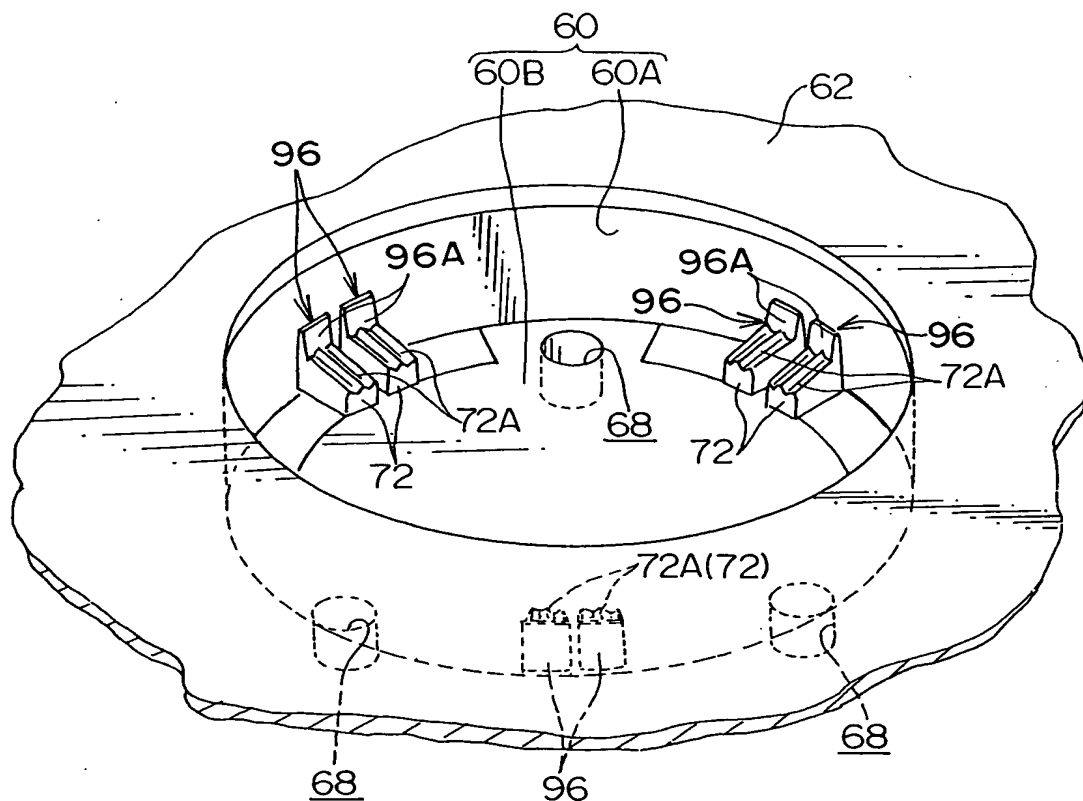


FIG. 10

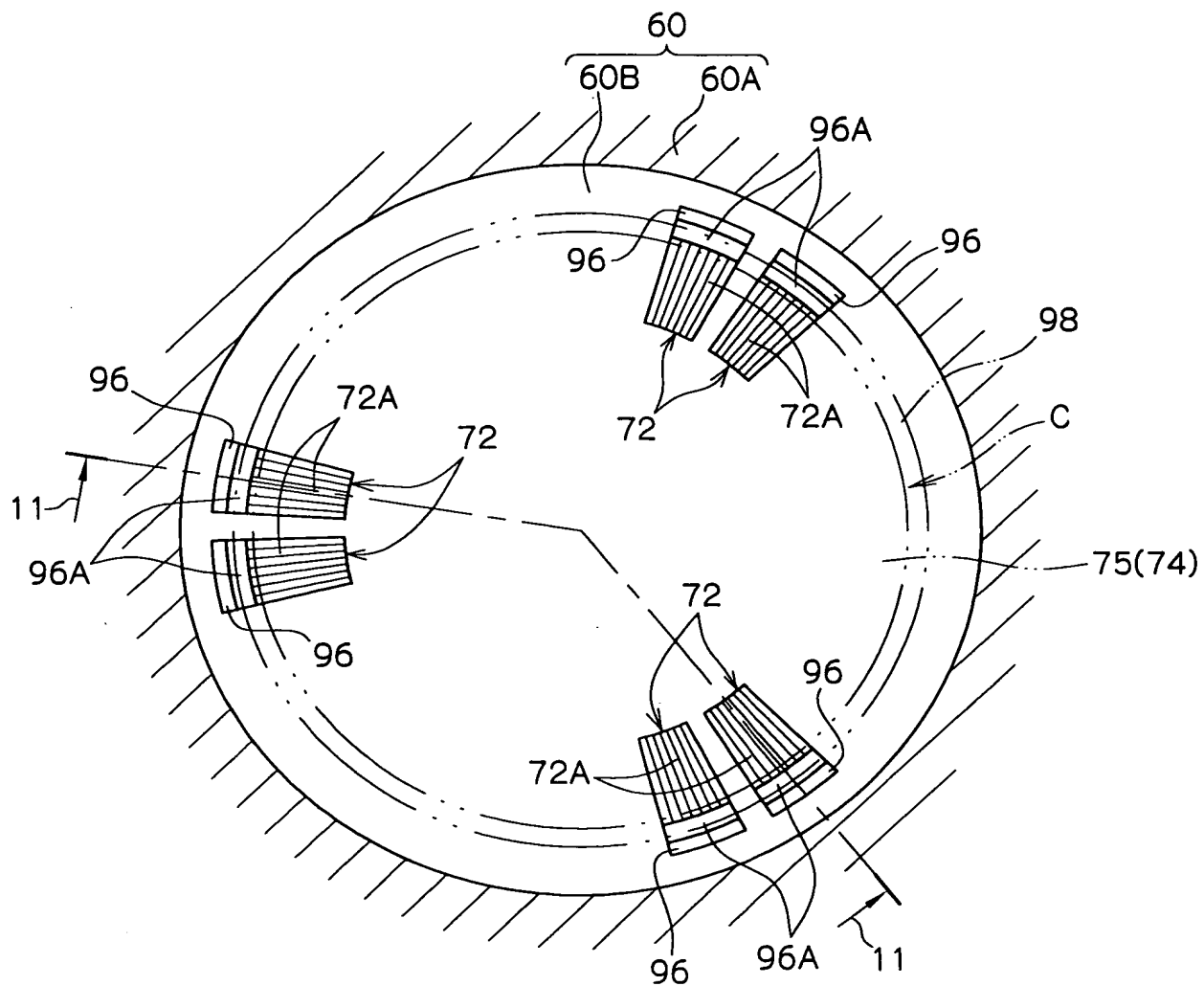
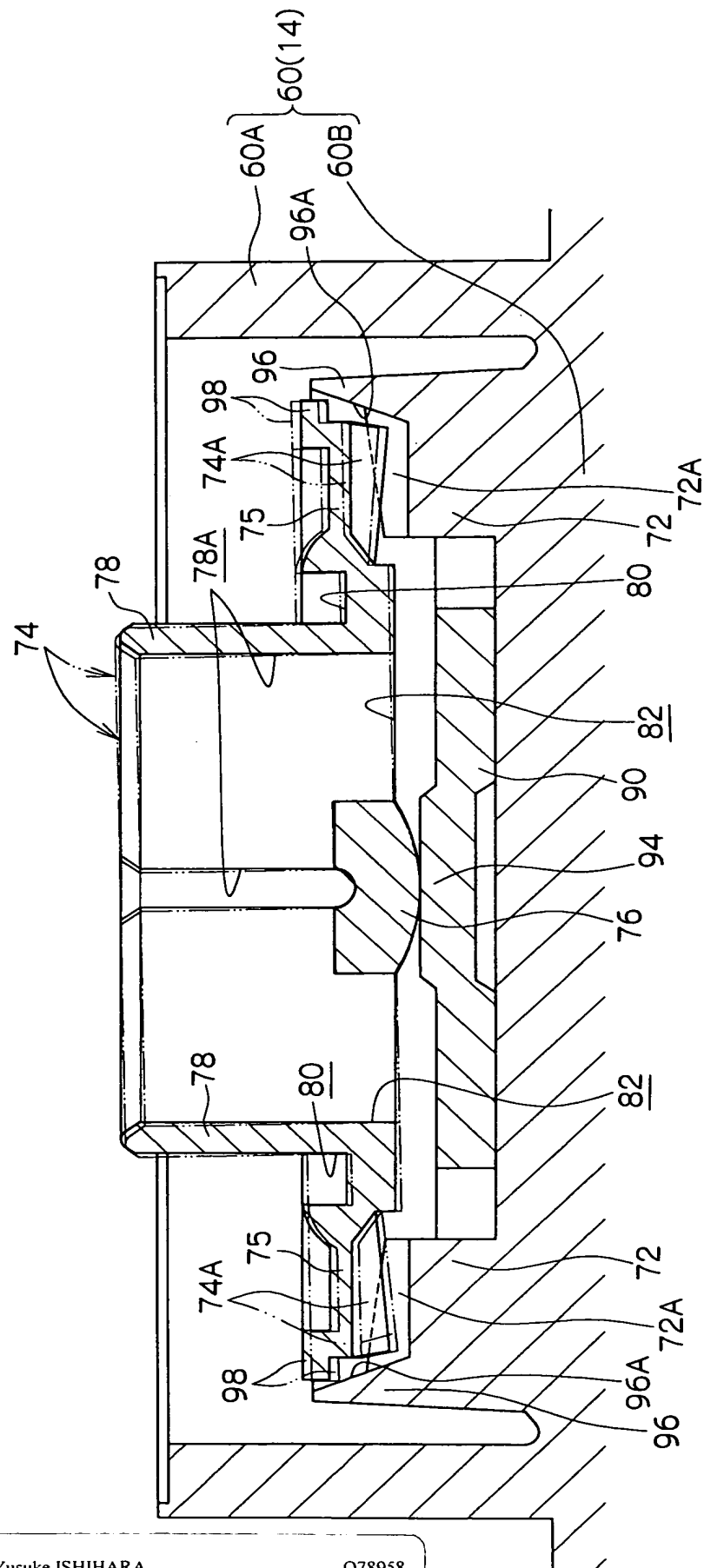


FIG.11



[illegible]

200

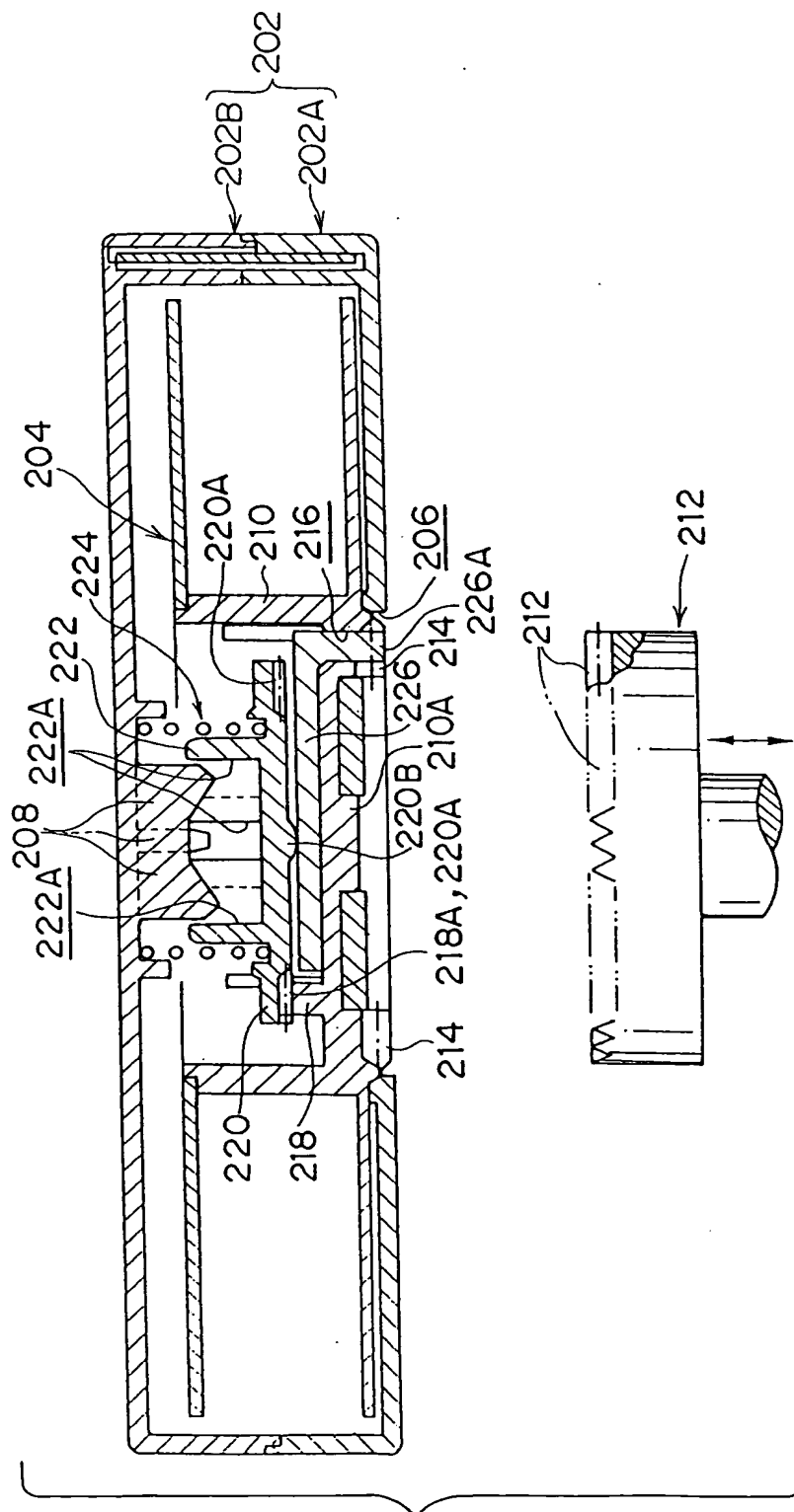


FIG.14
PRIOR ART

